

WHAT IS CLAIMED IS:

1. An apparatus, comprising:
a first printed circuit board portion including a lower-quality dielectric material;
and
a second printed circuit board portion coupled to the first portion, the second
5 portion including a higher-quality dielectric material.
2. The apparatus of claim 1, wherein the second portion is integrated into a
solderjoint interface area between a device and the first portion.
- 10 3. The apparatus of claim 1, further including:
a device electrically coupled to the second portion via a solderjoint interface.
4. The apparatus of claim 3, wherein the device comprises at least one of: (i) a
socket, (ii) a package, (iii) a chip-set, (iv) a processor, (v) a peripheral interface, and (vi)
15 an input output device.
5. The apparatus of claim 3, wherein the entire device is electrically coupled to
the second portion.
- 20 6. The apparatus of claim 3, wherein part of the device is not electrically coupled
to the second portion.

7. The apparatus of claim 6, wherein the second portion includes a hole, and part of the device is electrically coupled to the first portion through the hole.

8. The apparatus of claim 3, wherein part of the device is electrically coupled to
5 both the first and second portions.

9. The apparatus of claim 3, further comprising:
a second portion trace electrically coupled to the solderjoint interface.

10 10. The apparatus of claim 3, further comprising:
another device electrically coupled to the second portion, wherein signaling between the devices through the second portion is improved as compared to the first portion.

15 11. The apparatus of claim 1, wherein the higher-quality dielectric material is more homogeneous as compared to the lower-quality dielectric material.

12. The apparatus of claim 1, wherein the second portion is thinner as compared to the first portion.

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13. A method, comprising:

forming traces on a first printed circuit board portion that includes a lower-quality dielectric material; and

forming traces on a second printed circuit board portion coupled to the first
25 portion, the second portion including a higher-quality dielectric material.

14. The method of claim 13, wherein the second portion is integrated into a solderjoint interface area between a device and the first portion.

5 15. A method, comprising:

 providing signals through traces on a first printed circuit board portion that includes a lower-quality dielectric material; and

 providing signals through traces on a second printed circuit board portion coupled to the first portion, the second portion including a higher-quality dielectric material.

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16. The method of claim 15, wherein the second portion is integrated into a solderjoint interface area between a device and the first portion.

17. An apparatus, comprising:

15 a lower-quality printed circuit board portion; and

 a higher-quality printed circuit board portion integrated into a solderjoint interface area between a device and the first portion.

18. The apparatus of claim 17, wherein the higher-quality portion is thinner and
20 includes a dielectric material that is more homogeneous as compared to the lower-quality portion.

19. A system, comprising:

 a power supply to receive alternating current power and to provide direct current
25 power; and

a printed circuit board to receive the direct current power from the power supply and including:

a first printed circuit board portion including a lower-quality dielectric material, and

5 a second printed circuit board portion coupled to the first portion, the second portion including a higher-quality dielectric material.

20. The system of claim 19, wherein the second portion is integrated into a solderjoint interface area between a processor and the first portion.